

PMN34LN

μTrenchMOS™ logic level FET

Rev. 01 — 21 March 2003

Product data

1. Product profile

1.1 Description

N-channel enhancement mode field-effect transistor in a plastic package using TrenchMOS™ technology.

Product availability:

PMN34LN in SOT457 (TSOP6).

1.2 Features

- Low on-state resistance in small surface mount package.

1.3 Applications

- DC-to-DC primary side.

1.4 Quick reference data

- $V_{DS} \leq 20 \text{ V}$
- $I_D \leq 5.7 \text{ A}$
- $P_{tot} \leq 1.75 \text{ W}$
- $R_{DS(on)} \leq 34 \text{ m}\Omega$

2. Pinning information

Table 1: Pinning - SOT457 (TSOP6), simplified outline and symbol

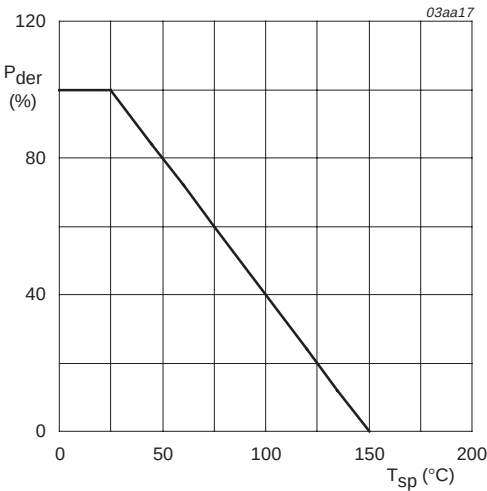
Pin	Description	Simplified outline	Symbol
1,2,5,6	drain (d)	Top view MBK092 SOT457 (TSOP6)	MBB076
3	gate (g)		
4	source (s)		

3. Limiting values

Table 2: Limiting values

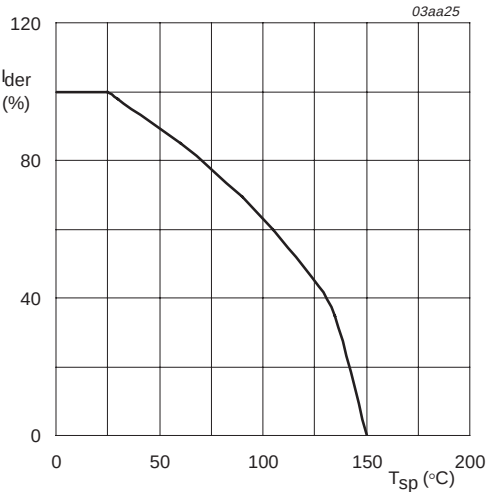
In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{DS}	drain-source voltage (DC)	$25\text{ }^{\circ}\text{C} \leq T_j \leq 150\text{ }^{\circ}\text{C}$	-	20	V
V_{DGR}	drain-gate voltage (DC)	$25\text{ }^{\circ}\text{C} \leq T_j \leq 150\text{ }^{\circ}\text{C}$; $R_{GS} = 20\text{ k}\Omega$	-	20	V
V_{GS}	gate-source voltage (DC)		-	± 15	V
I_D	drain current (DC)	$T_{sp} = 25\text{ }^{\circ}\text{C}$; $V_{GS} = 10\text{ V}$; Figure 2 and 3	-	5.7	A
		$T_{sp} = 100\text{ }^{\circ}\text{C}$; $V_{GS} = 10\text{ V}$; Figure 2	-	3.6	A
I_{DM}	peak drain current	$T_{sp} = 25\text{ }^{\circ}\text{C}$; pulsed; $t_p \leq 10\text{ }\mu\text{s}$; Figure 3	-	22.9	A
P_{tot}	total power dissipation	$T_{sp} = 25\text{ }^{\circ}\text{C}$; Figure 1	-	1.75	W
T_{stg}	storage temperature		-55	+150	$^{\circ}\text{C}$
T_j	junction temperature		-55	+150	$^{\circ}\text{C}$
Source-drain diode					
I_S	source (diode forward) current (DC)	$T_{sp} = 25\text{ }^{\circ}\text{C}$	-	1.45	A
I_{SM}	peak source (diode forward) current	$T_{sp} = 25\text{ }^{\circ}\text{C}$; pulsed; $t_p \leq 10\text{ }\mu\text{s}$	-	5.95	A



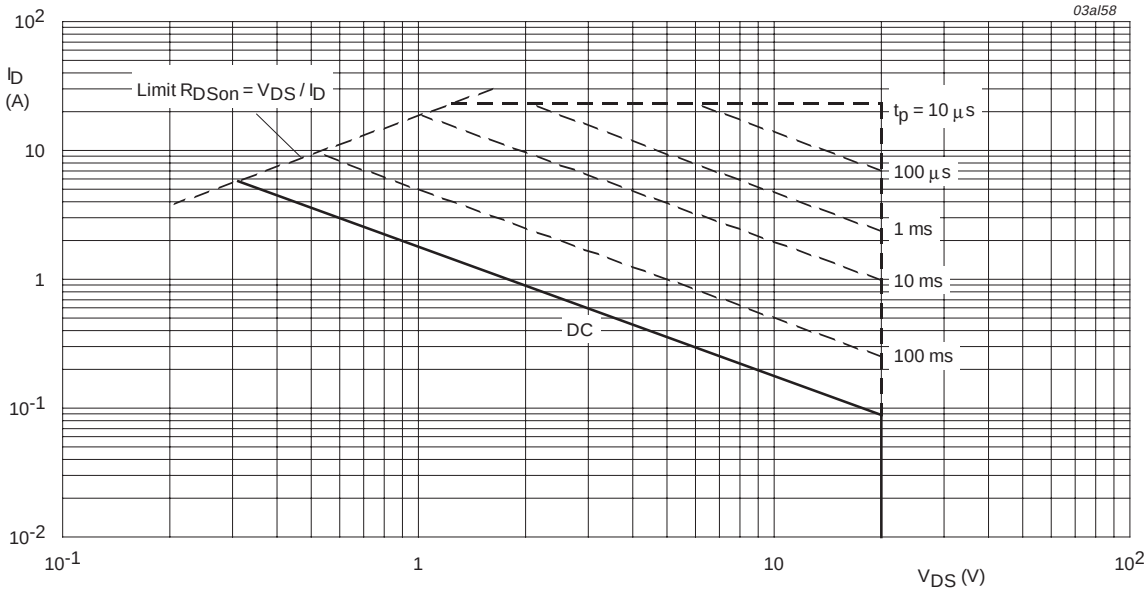
$$P_{der} = \frac{P_{tot}}{P_{tot(25^{\circ}C)}} \times 100\%$$

Fig 1. Normalized total power dissipation as a function of solder point temperature.



$$I_{der} = \frac{I_D}{I_{D(25^{\circ}C)}} \times 100\%$$

Fig 2. Normalized continuous drain current as a function of solder point temperature.



$T_{sp} = 25$ °C; I_{DM} is single pulse; $V_{GS} = 10$ V

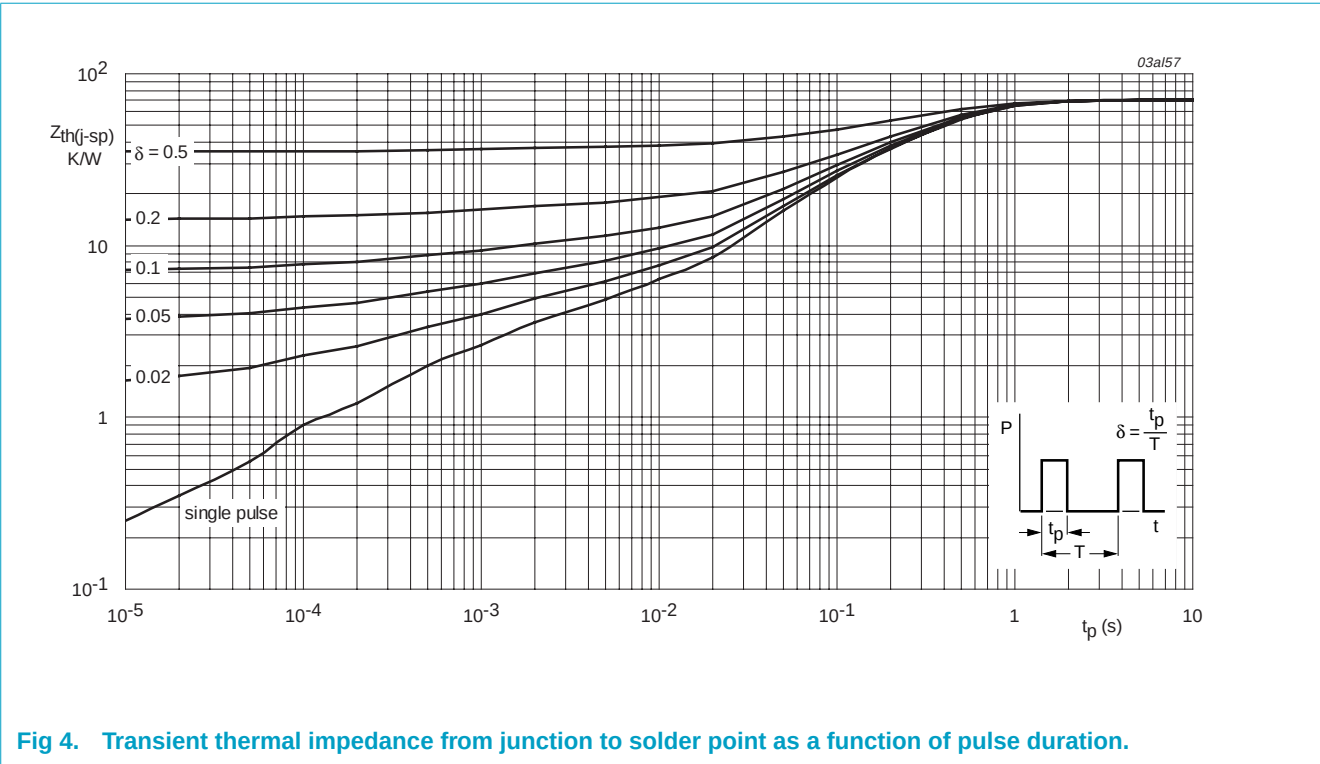
Fig 3. Safe operating area; continuous and peak drain currents as a function of drain-source voltage.

4. Thermal characteristics

Table 3: Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-sp)}$	thermal resistance from junction to solder point	Figure 4	-	-	70	K/W

4.1 Transient thermal impedance

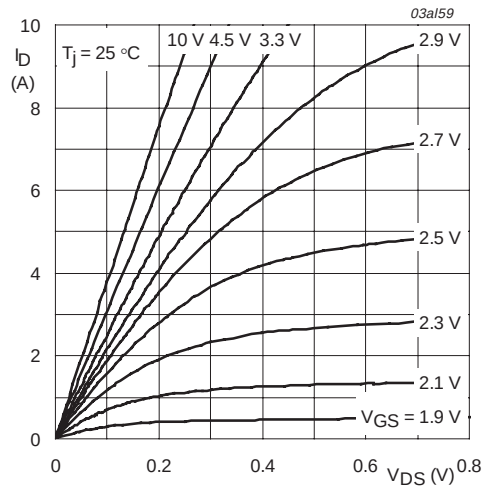


5. Characteristics

Table 4: Characteristics

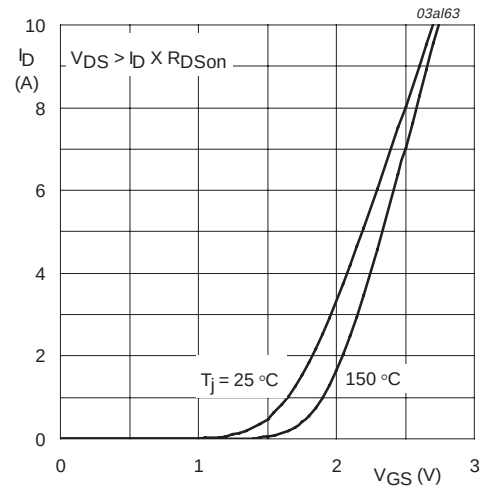
$T_j = 25\text{ °C}$ unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static characteristics						
$V_{(BR)DSS}$	drain-source breakdown voltage	$I_D = 250\text{ }\mu\text{A}$; $V_{GS} = 0\text{ V}$				
		$T_j = 25\text{ °C}$	20	-	-	V
		$T_j = -55\text{ °C}$	18	-	-	V
$V_{GS(th)}$	gate-source threshold voltage	$I_D = 1\text{ mA}$; $V_{DS} = V_{GS}$; Figure 9				
		$T_j = 25\text{ °C}$	1	-	2	V
		$T_j = 150\text{ °C}$	0.6	-	-	V
		$T_j = -55\text{ °C}$	-	-	2.3	V
I_{DSS}	drain-source leakage current	$V_{DS} = 16\text{ V}$; $V_{GS} = 0\text{ V}$				
		$T_j = 25\text{ °C}$	-	-	1	μA
		$T_j = 150\text{ °C}$	-	-	100	μA
I_{GSS}	gate-source leakage current	$V_{GS} = \pm 15\text{ V}$; $V_{DS} = 0\text{ V}$	-	10	100	nA
$R_{DS(on)}$	drain-source on-state resistance	$V_{GS} = 10\text{ V}$; $I_D = 2.5\text{ A}$; Figure 7 and 8				
		$T_j = 25\text{ °C}$	-	28	34	m Ω
		$T_j = 150\text{ °C}$	-	44.8	54.4	m Ω
		$V_{GS} = 4.5\text{ V}$; $I_D = 2\text{ A}$; Figure 7 and 8		34	40	m Ω
Dynamic characteristics						
$Q_{g(tot)}$	total gate charge	$I_D = 6\text{ A}$; $V_{DD} = 10\text{ V}$; $V_{GS} = 10\text{ V}$; Figure 13	-	13.1	-	nC
Q_{gs}	gate-source charge		-	1.9	-	nC
Q_{gd}	gate-drain (Miller) charge		-	2.3	-	nC
C_{iss}	input capacitance	$V_{GS} = 0\text{ V}$; $V_{DS} = 20\text{ V}$; $f = 1\text{ MHz}$; Figure 11	-	500	-	pF
C_{oss}	output capacitance		-	170	-	pF
C_{rss}	reverse transfer capacitance		-	110	-	pF
$t_{d(on)}$	turn-on delay time	$V_{DD} = 10\text{ V}$; $R_D = 10\text{ }\Omega$; $V_{GS} = 4.5\text{ V}$; $R_G = 6\text{ }\Omega$	-	10	-	ns
t_r	rise time		-	14	-	ns
$t_{d(off)}$	turn-off delay time		-	23	-	ns
t_f	fall time		-	12	-	ns
Source-drain diode						
V_{SD}	source-drain (diode forward) voltage	$I_S = 1.7\text{ A}$; $V_{GS} = 0\text{ V}$; Figure 12	-	0.8	1.2	V



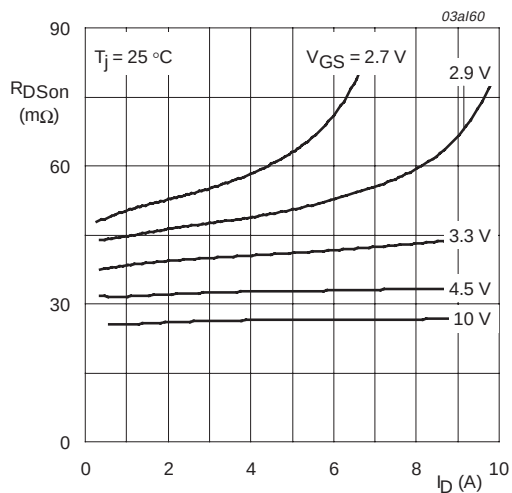
$T_j = 25^\circ\text{C}$

Fig 5. Output characteristics: drain current as a function of drain-source voltage; typical values.



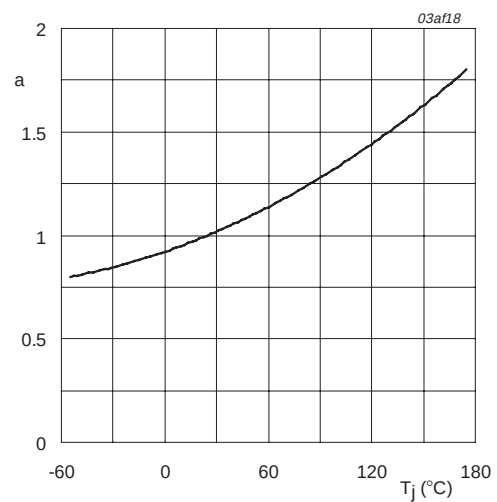
$T_j = 25^\circ\text{C}$ and 150°C ; $V_{DS} > I_D \times R_{DSon}$

Fig 6. Transfer characteristics: drain current as a function of gate-source voltage; typical values.



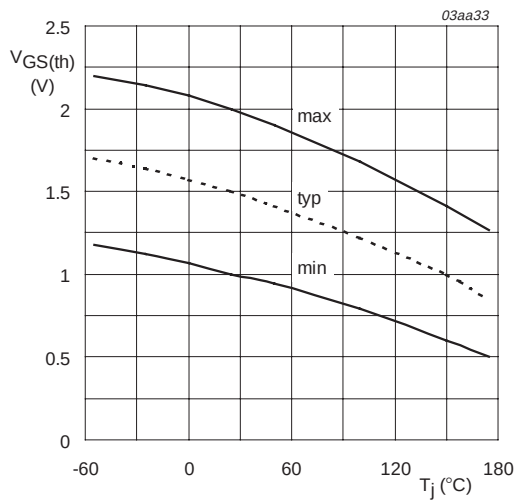
$T_j = 25^\circ\text{C}$

Fig 7. Drain-source on-state resistance as a function of drain current; typical values.



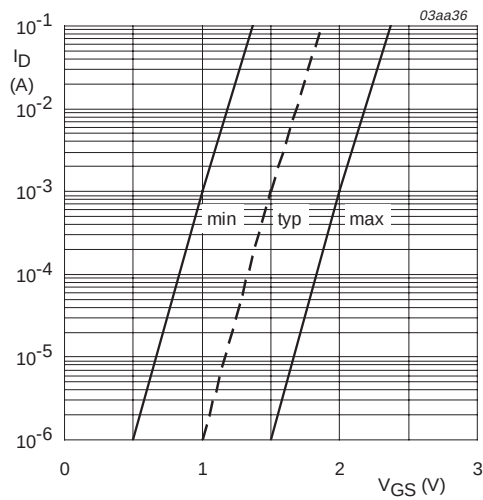
$$a = \frac{R_{DSon}}{R_{DSon}(25^\circ\text{C})}$$

Fig 8. Normalized drain-source on-state resistance factor as a function of junction temperature.



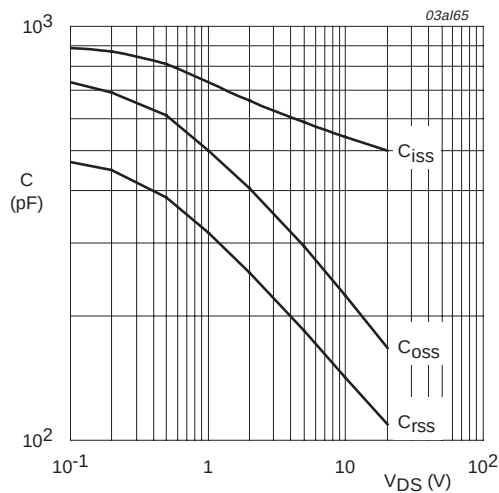
$I_D = 1 \text{ mA}$; $V_{DS} = V_{GS}$

Fig 9. Gate-source threshold voltage as a function of junction temperature.



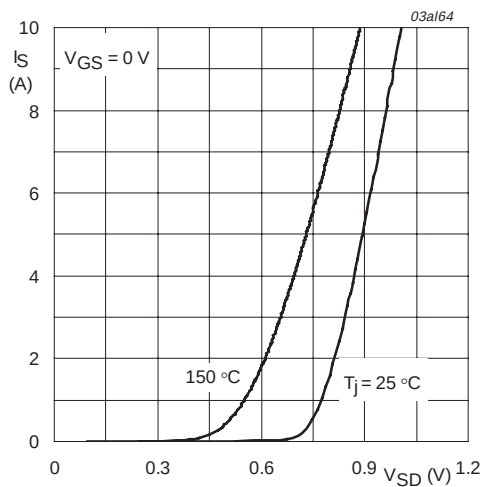
$T_j = 25 \text{ }^\circ\text{C}$

Fig 10. Sub-threshold drain current as a function of gate-source voltage.



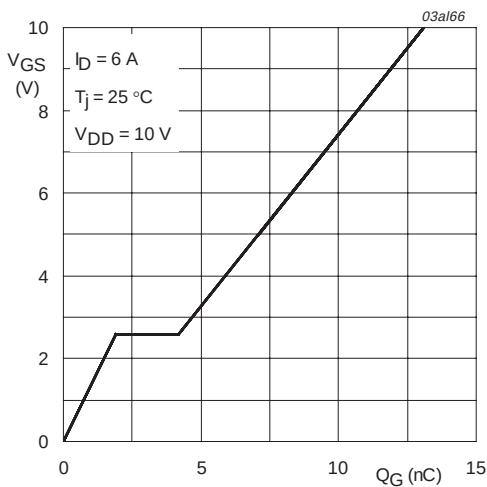
$V_{GS} = 0 \text{ V}$; $f = 1 \text{ MHz}$

Fig 11. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values.



$T_J = 25$ °C and 150 °C; $V_{GS} = 0$ V

Fig 12. Source (diode forward) current as a function of source-drain (diode forward) voltage; typical values.



$I_D = 6$ A; $V_{DD} = 10$ V

Fig 13. Gate-source voltage as a function of gate charge; typical values.

6. Package outline

Plastic surface mounted package; 6 leads

SOT457

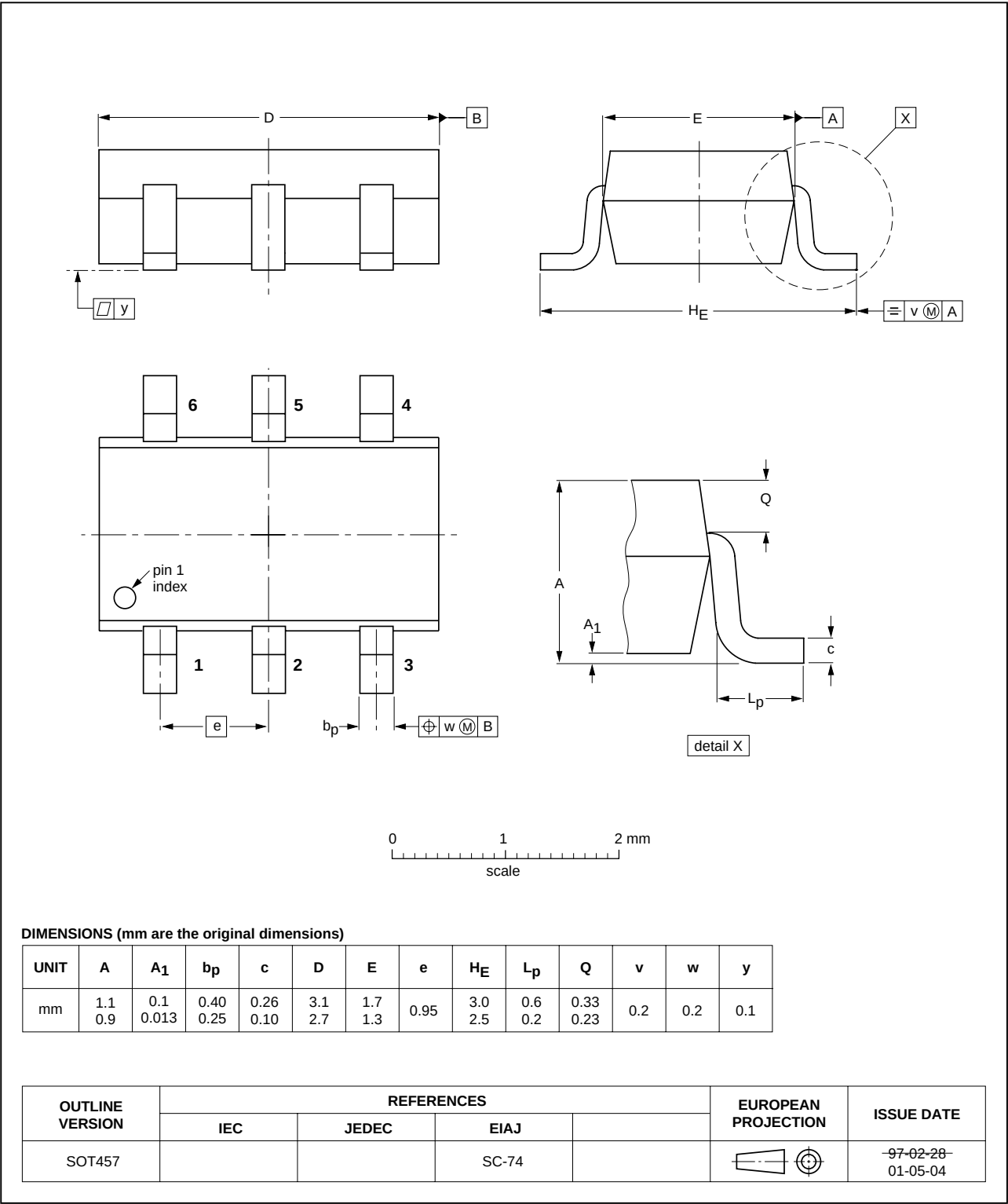


Fig 14. SOT457 (TSOP6).

7. Revision history

Table 5: Revision history

Rev	Date	CPCN	Description
01	20030321	-	Product data (9397 750 10938)

8. Data sheet status

Level	Data sheet status ^[1]	Product status ^{[2][3]}	Definition
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
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Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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